







IFNU231, IFNU232, IFNU233 Dual Matched N-Channel JFET

Features

InterFET N0016H Geometry

· Low Leakage: 10 pA Typical

• Low Input Capacitance: 3.5 pF Typical

· High Input Impedance

• Replacement for U231, U232, U233

RoHS Compliant

• SMT, TH, and Bare Die Package options.

Applications

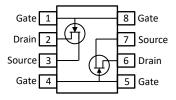
- · Low Noise Differential Amplifier
- Differential Amplifier
- · Wide-Band Amplifier

Description

The -50V InterFET IFNU231, IFNU232, and IFNU233 JFET's are targeted for low noise differential amplifier designs. Gate leakages are less than 10pA at room temperatures. The TO-71 package is hermetically sealed and suitable for military applications. Custom specifications, matching, and packaging options are available.

Source TO-71 Bottom View Source Gate 3 0 0 7 Gate Drain Source

SOIC8 Top View





Product Summary

| | Parameters | IFNU231 Min | IFNU232 Min | IFNU233 Min | Unit |
|----------------------|------------------------------------|-------------|-------------|-------------|------|
| BV_GSS | Gate to Source Breakdown Voltage | -50 | -50 | -50 | V |
| I _{DSS} | Drain to Source Saturation Current | 0.5 | 0.5 | 0.5 | mA |
| V _{GS(off)} | Gate to Source Cutoff Voltage | -0.5 | -0.5 | -0.5 | V |
| G _{FS} | Forward Transconductance | 0.6 | 0.6 | 0.6 | mS |

Ordering Information Custom Part and Binning Options Available

| Cracing Mornation Custom Fart and Billing Options Available | | | | | |
|---|-------------------------------------|-------|--------------------|--|--|
| Part Number | Description | Case | Packaging | | |
| IFNU231; IFNU232; IFNU233 | Through-Hole | TO-71 | Bulk | | |
| SMPU231; SMPU232; SMPU233 | Surface Mount | SOIC8 | Bulk | | |
| | 7" Tape and Reel: Max 500 Pieces | | Minimum 500 Pieces | | |
| SMPU231TR; SMPU232TR; SMPU233TR | 13" Tape and Reel: Max 2,500 Pieces | SOIC8 | Tape and Reel | | |
| | Chip Orientated Tray | | | | |
| IFNU231COT; IFNU232COT; IFNU233COT * | (COT Waffle Pack) | COT | 70/Waffle Pack | | |
| IFNU231CFT; IFNU232CFT; IFNU233CFT * | Chip Face-up Tray (CFT Waffle Pack) | CFT | 70/Waffle Pack | | |

^{*} Bare die packaged options are designed for matched specifications but not 100% tested



Disclaimer: It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.









Electrical Characteristics

Maximum Ratings (@ T_A = 25°C, Unless otherwise specified)

| | Parameters | Value | Unit |
|------------------|--|------------|-------|
| V_{RGS} | Reverse Gate Source and Gate Drain Voltage | -50 | V |
| I _{FG} | Continuous Forward Gate Current | 50 | mA |
| PD | Continuous Device Power Dissipation | 300 | mW |
| Р | Power Derating | 4.3 | mW/°C |
| TJ | Operating Junction Temperature | -55 to 125 | °C |
| T _{STG} | Storage Temperature | -65 to 150 | °C |

Static Characteristics (@ TA = 25°C, Unless otherwise specified)

| | | | IFNU231, IFNU232, IFNU233 | | |
|----------------------|---------------------------------------|---|---------------------------|--------------|----------|
| | Parameters | Conditions | Min | Max | Unit |
| V _{(BR)GSS} | Gate to Source Breakdown Voltage | V _{DS} = 0V, I _G = -1μA | -50 | | V |
| I _{GSS} | Gate to Source Reverse Current | $V_{GS} = -30V$, $V_{DS} = 0V$, $T_A = 25$ °C $V_{GS} = -30V$, $V_{DS} = 0V$, $T_A = 150$ °C | | -100 -500 | pA nA |
| V _{GS(OFF)} | Gate to Source Cutoff Voltage | V _{DS} = 20V, I _D = 1nA | -0.5 | -4.5 | V |
| V _{GS} | Gate to Source Voltage | V _{DS} = 20V, I _D = 200μA | -0.3 | -4 | V |
| I _{DSS} | Drain to Source Saturation Current | $V_{DS} = 20V$, $V_{GS} = 0V$ (Pulsed) | 0.5 | 5 | mA |
| lg | Gate Current | V _{DS} = 20V, I _D = 200μA, T _A = 25°C V _{DS} = 20V, I _D = 200μA, T _A = 125°C | | -50 -250 | pA nA |

Dynamic Characteristics (@ TA = 25°C, Unless otherwise specified)

| | | | | IFNU231, IFNU232, IFNU233 | | |
|--|---|---|-------------------------------|---------------------------|-----|--------|
| | Parameters | Conditions | | Min | Max | Unit |
| G _{FS} | Forward Transconductance | V _{DS} = 20V, I _D = 200μA, | f = 1kHz | 0.6 | 1.6 | mS |
| Gos | Output Conductance | $V_{DS} = 20V$, $I_{D} = 200\mu A$, | f = 1kHz | | 10 | μS |
| C _{iss} | Input Capacitance | $V_{DS} = 20V, V_{GS} = 0V, f$ | = 1MHz | | 6 | pF |
| Crss | Reverse Transfer Capacitance | $V_{DS} = 20V, V_{GS} = 0V, f$ | = 1MHz | | 2 | pF |
| e _n | Equivalent Circuit Input Noise Voltage | V _{DS} = 20V, V _{GS} = 0V, f : | = 100Hz | | 80 | nV/√Hz |
| V _{GS1} | Differential Gate Source Voltage | V _{DS} = 20V, I _D = 200μA | IFNU231 IFNU232 IFNU233 | : 1 1 | 0 | mV |
| V _{GS1} -V _{GS2} ∆T | Differential Gate Source Voltage with Temperature | $V_{DS} = 20V, I_{D} = 200\mu A,$ $T_{A} = -55^{\circ}C, T_{B} = 25^{\circ}C,$ $T_{C} = 125^{\circ}C$ | IFNU231 IFNU232 IFNU233 | | .5 | mV/°C |



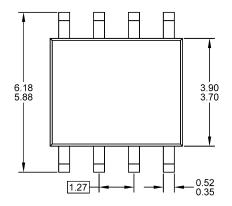


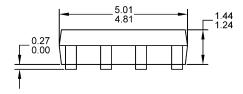


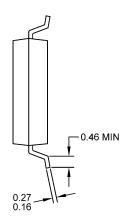


SOIC8 Mechanical and Layout Data

Package Outline Data

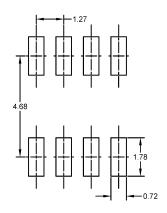






- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.21 grams
- 3. Molded plastic case UL 94V-0 rated
- For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

Suggested Pad Layout



- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.



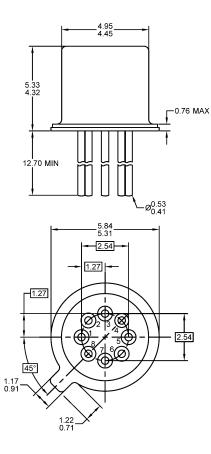






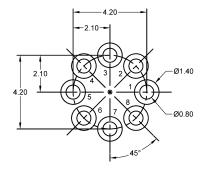
TO-71 Mechanical and Layout Data

Package Outline Data



- 1. All linear dimensions are in millimeters.
- Eight leaded device. Not all leads are shown in drawing views.
- 3. Some package configurations will not populate pin 8 and/or pin 4.
- 4. Package weight approximately 0.35 grams
- Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

Suggested Bent Lead Through-Hole Layout



- 1. All linear dimensions are in millimeters.
- Pads 8 and/or pad 4 can be eliminated for devices with less pins.
- The suggested land pattern dimensions have been provided as an eight pin bent lead reference only. A more robust pattern may be desired for wave soldering or reduced pin count.

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